



# Product Change Notification

## #111111-01

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

### Intel Mobile Communications Contacts

Americas Email: [IMC.PCN.ASMO@intel.com](mailto:IMC.PCN.ASMO@intel.com)  
Asia Pacific Email: [IMC.PCN.APAC@intel.com](mailto:IMC.PCN.APAC@intel.com)  
Europe Email: [IMC.PCN.EMEA@intel.com](mailto:IMC.PCN.EMEA@intel.com)  
Japan Email: [IMC.PCN.IJKK@intel.com](mailto:IMC.PCN.IJKK@intel.com)  
Korea Email: [IMC.PCN.KOREA@intel.com](mailto:IMC.PCN.KOREA@intel.com)

Copyright © Intel Corporation 2011. Other names and brands may be claimed as the property of others.

Learn how to use Intel Trade Marks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.



# Product Change Notification

**Change Notification #:** 111111-01  
**Change Title:** Intel® SMARTi™ UE2, PMB5712A1, PCN 111111-01, Manufacturing Site, Material Change, Change to Overmold eWLB process, STATS ChipPAC, Reason for Revision: Removing Device Description Document

**Date of Publication:** November 24 , 2011

## Key Characteristics of the Change:

Manufacturing Site

## Forecasted Key Milestones:

<b>Date of Samples Availability:</b>	December 21, 2011
<b>Date of Qualification Data Availability:</b>	February 16, 2012
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	February 29, 2012

## Description of Change to the Customer:

In order to improve eWLB mechanical robustness and harmonize the eWLB process landscape, Intel Mobile Communications will be introducing the overmold eWLB process for Smarti™ UE2 for the package backend location – STATS ChipPAC.

## Customer Impact of Change and Recommended Action:

Intel Mobile Communications does not change the package size specifications, and does not anticipate any change in function or reliability (reliability to be documented via qualification report) and expects substantial improvement in mechanical robustness of the package. STATS ChipPAC is a qualified Manufacturing Site for IMC.

Please contact your local Intel Mobile Communications representative for further technical questions.

## Additional Files/Information Referenced:

Associated with this change and notification is the Information Package for SMARTi™ UE2.

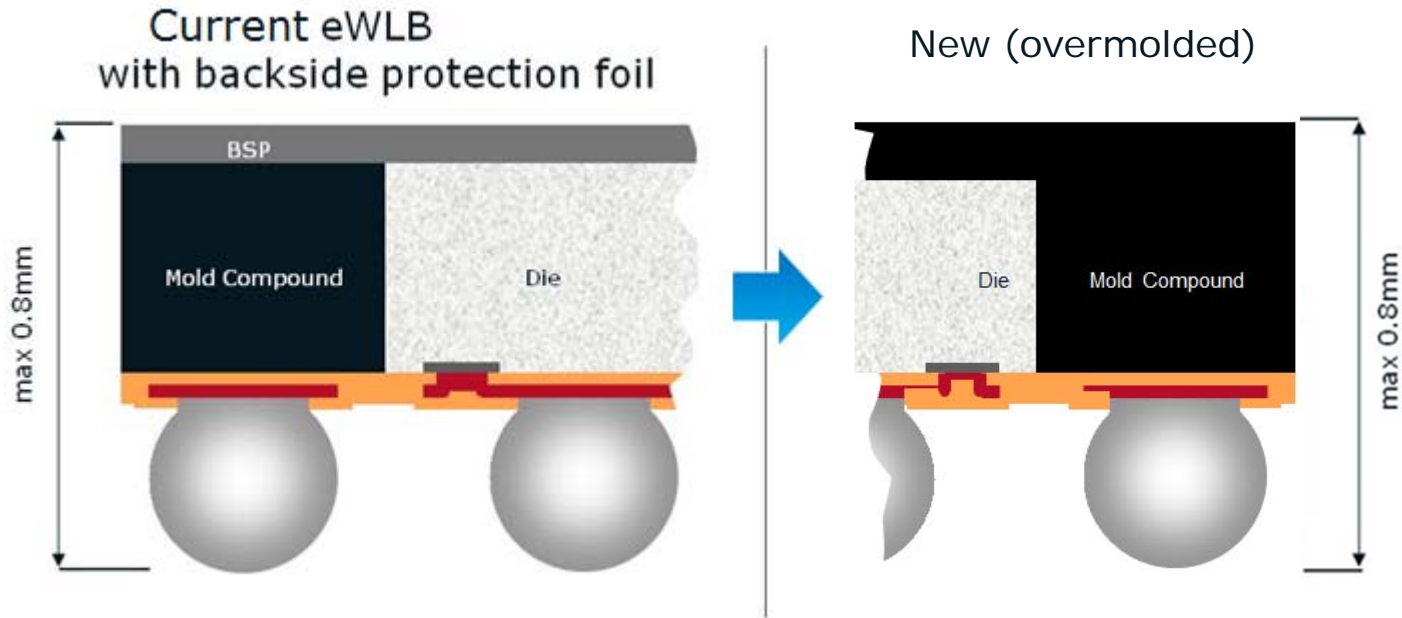
## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code
Intel® SMARTi™ UE2	PMB5712A1

## PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 24, 2011	00	Originally Published PCN
December 20, 2011	01	Removing the Device Description document

# Change description



- Conversion to an overmold process.
- The specified maximum package thickness will remain the same @ 0.8mm.
- All package related qualification test will be performed as verification of the change